2.280 (.090)

2.280 (.090)

BOTTOM VIEW

2.660 (.105)

ALTERNATE BOTTOM VIEW

Scale 4:1

- Generic Land Pattern -
Land Pattern is applicable to
both bottom side styles.

8

3.900 (.153)

6.000 (.236)

.835±.420

.203 (.008)

PIN 1 INDICATOR

TOP VIEW

4.900 (1.93)

.070 (.003)

1.27 BSC
(.050)

.420 (.016)

1.550 (.060)

SIDE VIEW

Notes:
1. Base Metal - Copper Olin 194
2. Lead Finish
   Basic PN - Sn/Pb Sn =>80%
   Z option - 100% Matte Sn - .01 (.0004) thk min
3. Devices may be received with either backside
   pattern shown above.

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN mm (inches)
PER ANSI Y14.5M-1982.
TOLERANCES ARE:
DECIMAL   ANGLE
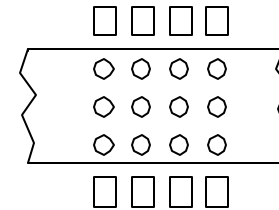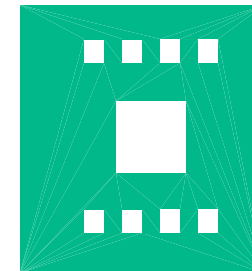.XX ±.12 (.005) ±1/2°
.XXX ±.05 (.002)

MATERIAL(S):
See Notes

FINISH:
See Notes

- Do Not Scale Hard Copy -

Scale 4:1

- Generic Solder Mask Opening -
Solder mask opening is applicable to
both bottom side styles.
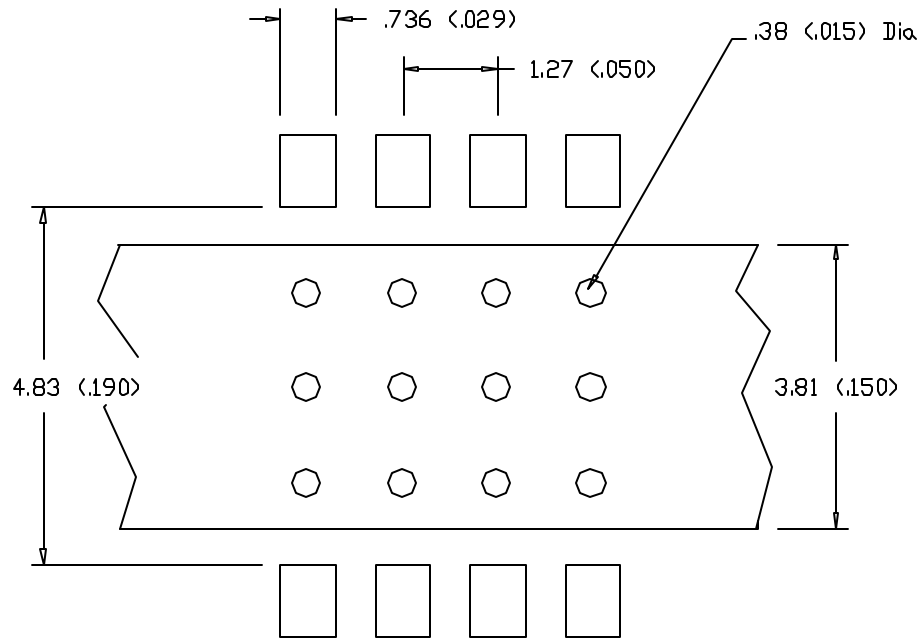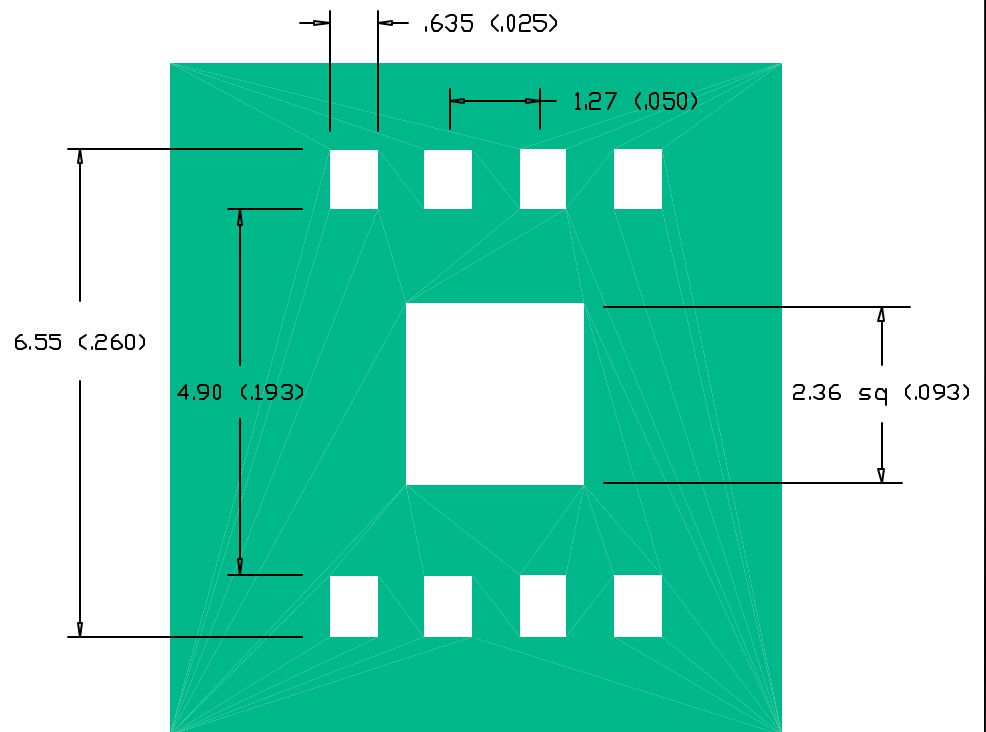
SIRENZA
MICRODEVICES

Package Type:

SOIC-8 with EPAD
SMDI Package Type: XXX-XX18

Ref Dwg No.
MPO-101644

Sht 1 of 2

REV
E

.736 (.029)

1.27 (.050)

.38 (.015) Dia

4.83 (.190)

3.81 (.150)

Scale 10:1

- Generic Land Pattern -
Land Pattern is applicable to
both bottom side styles.

.635 (.025)

1.27 (.050)

6.55 (.260)

4.90 (.193)

2.36 sq (.093)

Scale 10:1

- Generic Solder Mask Opening -
Solder mask opening is applicable to
both bottom side styles.

- Do Not Scale Hard Copy -

SIRENZA MICRODEVICES

Package Type:

SOIC-8 with EPAD

SMDI Package Type: XXX-XX18

Ref Dwg No.		REV
MPO-101644	Sht 2 of 2	E